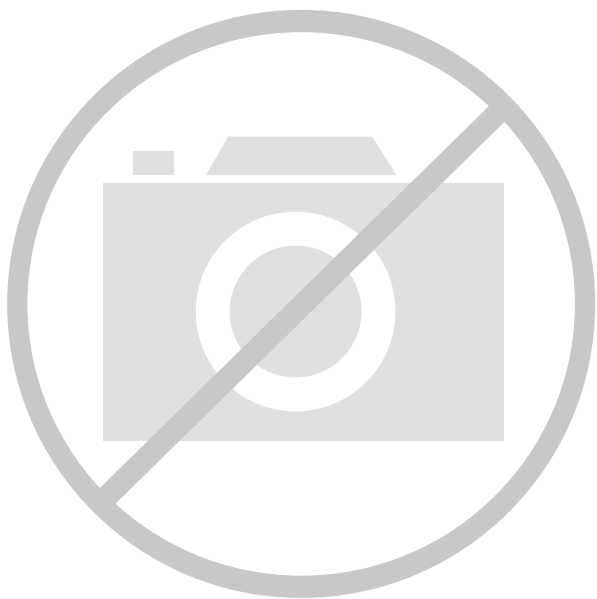




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	7776
Number of Logic Elements/Cells	34992
Total RAM Bits	589824
Number of I/O	512
Number of Gates	2188742
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	680-LBGA Exposed Pad
Supplier Device Package	680-FTEBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1600e-8fg680c

Architectural Description

Virtex-E Array

The Virtex-E user-programmable gate array, shown in **Figure 1**, comprises two major configurable elements: configurable logic blocks (CLBs) and input/output blocks (IOBs).

- CLBs provide the functional elements for constructing logic
- IOBs provide the interface between the package pins and the CLBs

CLBs interconnect through a general routing matrix (GRM). The GRM comprises an array of routing switches located at the intersections of horizontal and vertical routing channels. Each CLB nests into a VersaBlock™ that also provides local routing resources to connect the CLB to the GRM.

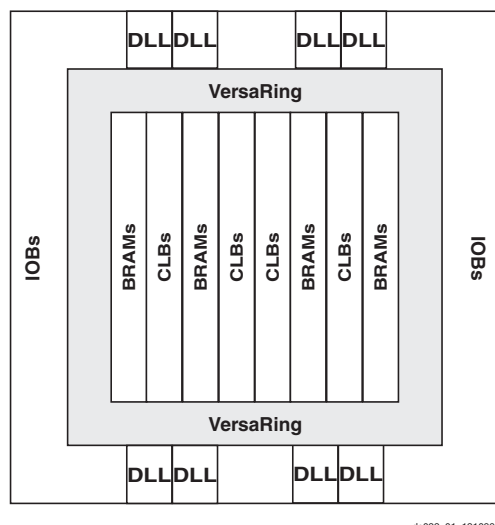


Figure 1: Virtex-E Architecture Overview

The VersaRing™ I/O interface provides additional routing resources around the periphery of the device. This routing improves I/O routability and facilitates pin locking.

The Virtex-E architecture also includes the following circuits that connect to the GRM.

- Dedicated block memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- 3-State buffers (BUFTs) associated with each CLB that drive dedicated segmentable horizontal routing resources

Values stored in static memory cells control the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Input/Output Block

The Virtex-E IOB, **Figure 2**, features SelectI/O+ inputs and outputs that support a wide variety of I/O signalling standards, see **Table 1**.

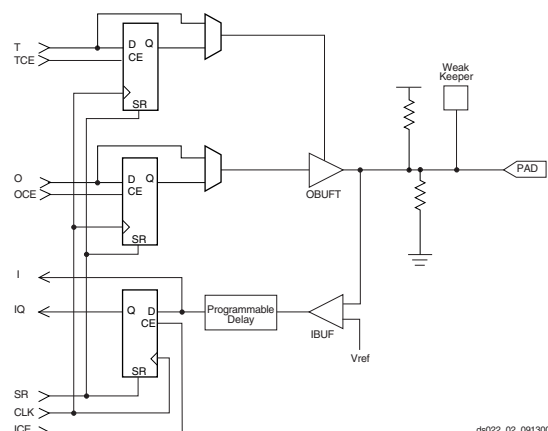


Figure 2: Virtex-E Input/Output Block (IOB)

The three IOB storage elements function either as edge-triggered D-type flip-flops or as level-sensitive latches. Each IOB has a clock signal (CLK) shared by the three flip-flops and independent clock enable signals for each flip-flop.

For in-circuit debugging, an optional download and read-back cable is available. This cable connects the FPGA in the target system to a PC or workstation. After downloading the design into the FPGA, the designer can single-step the

logic, readback the contents of the flip-flops, and so observe the internal logic state. Simple modifications can be downloaded into the system in a matter of minutes.

Configuration

Virtex-E devices are configured by loading configuration data into the internal configuration memory. Note that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Some of the pins used for configuration are dedicated pins, while others can be re-used as general purpose inputs and outputs once configuration is complete.

The following are dedicated pins:

- Mode pins (M2, M1, M0)
- Configuration clock pin (CCLK)
- PROGRAM pin
- DONE pin
- Boundary Scan pins (TDI, TDO, TMS, TCK)

Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or can be generated externally and provided to the FPGA as an input. The PROGRAM pin must be pulled High prior to reconfiguration.

Note that some configuration pins can act as outputs. For correct operation, these pins require a V_{CCO} of 3.3 V or 2.5 V. At 3.3 V the pins operate as LVTTTL, and at 2.5 V they

operate as LVCMOS. All affected pins fall in banks 2 or 3. The configuration pins needed for SelectMap (CS, Write) are located in bank 1.

Configuration Modes

Virtex-E supports the following four configuration modes.

- Slave-serial mode
- Master-serial mode
- SelectMAP mode
- Boundary Scan mode (JTAG)

The Configuration mode pins (M2, M1, M0) select among these configuration modes with the option in each case of having the IOB pins either pulled up or left floating prior to configuration. The selection codes are listed in [Table 8](#).

Configuration through the Boundary Scan port is always available, independent of the mode selection. Selecting the Boundary Scan mode simply turns off the other modes. The three mode pins have internal pull-up resistors, and default to a logic High if left unconnected. However, it is recommended to drive the configuration mode pins externally.

Table 8: Configuration Codes

Configuration Mode	M2 ⁽¹⁾	M1	M0	CCLK Direction	Data Width	Serial D _{out}	Configuration Pull-ups ⁽¹⁾
Master-serial mode	0	0	0	Out	1	Yes	No
Boundary Scan mode	1	0	1	N/A	1	No	No
SelectMAP mode	1	1	0	In	8	No	No
Slave-serial mode	1	1	1	In	1	Yes	No
Master-serial mode	1	0	0	Out	1	Yes	Yes
Boundary Scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Notes:

1. M2 is sampled continuously from power up until the end of the configuration. Toggling M2 while INIT is being held externally Low can cause the configuration pull-up settings to change.

Table 9 lists the total number of bits required to configure each device.

Table 9: Virtex-E Bitstream Lengths

Device	# of Configuration Bits
XCV50E	630,048
XCV100E	863,840
XCV200E	1,442,016
XCV300E	1,875,648
XCV400E	2,693,440
XCV600E	3,961,632
XCV1000E	6,587,520
XCV1600E	8,308,992
XCV2000E	10,159,648
XCV2600E	12,922,336
XCV3200E	16,283,712

Slave-Serial Mode

In slave-serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other source of serial configuration data. The serial bitstream must be set up at the DIN input pin a short time before each rising edge of an externally generated CCLK.

Table 10: Master/Slave Serial Mode Programming Switching

	Description	Figure References	Symbol	Values	Units
CCLK	DIN setup/hold, slave mode	1/2	T_{DCC}/T_{CCD}	5.0 / 0.0	ns, min
	DIN setup/hold, master mode	1/2	T_{DSCK}/T_{CKDS}	5.0 / 0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum Frequency		F_{CC}	66	MHz, max
	Frequency Tolerance, master mode with respect to nominal			+45% –30%	

For more detailed information on serial PROMs, see the PROM data sheet at <http://www.xilinx.com/bvdocs/publications/ds026.pdf>.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed to the DOUT pin. The maximum capacity for a single LOUT/DOUT write is $2^{20}-1$ (1,048,575) 32-bit words, or 33,554,400 bits. The data on the DOUT pin changes on the rising edge of CCLK.

The change of DOUT on the rising edge of CCLK differs from previous families, but does not cause a problem for mixed configuration chains. This change was made to improve serial configuration rates for Virtex and Virtex-E only chains.

Figure 13 shows a full master/slave system. A Virtex-E device in slave-serial mode should be connected as shown in the right-most device.

Slave-serial mode is selected by applying <111> or <011> to the mode pins (M2, M1, M0). A weak pull-up on the mode pins makes slave serial the default mode if the pins are left unconnected. However, it is recommended to drive the configuration mode pins externally. Figure 14 shows slave-serial mode programming switching characteristics.

Table 10 provides more detail about the characteristics shown in Figure 14. Configuration must be delayed until the INIT pins of all daisy-chained FPGAs are High.

Input termination techniques include the following.

- None
- Parallel (Shunt)

These termination techniques can be applied in any combination. A generic example of each combination of termination methods appears in **Figure 43**.

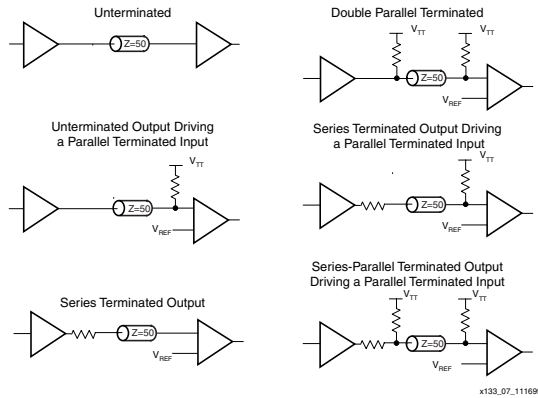


Figure 43: Overview of Standard Input and Output Termination Methods

Simultaneous Switching Guidelines

Ground bounce can occur with high-speed digital ICs when multiple outputs change states simultaneously, causing undesired transient behavior on an output, or in the internal logic. This problem is also referred to as the Simultaneous Switching Output (SSO) problem.

Ground bounce is primarily due to current changes in the combined inductance of ground pins, bond wires, and ground metallization. The IC internal ground level deviates from the external system ground level for a short duration (a few nanoseconds) after multiple outputs change state simultaneously.

Ground bounce affects stable Low outputs and all inputs because they interpret the incoming signal by comparing it to the internal ground. If the ground bounce amplitude exceeds the actual instantaneous noise margin, then a non-changing input can be interpreted as a short pulse with a polarity opposite to the ground bounce.

Table 21 provides guidelines for the maximum number of simultaneously switching outputs allowed per output power/ground pair to avoid the effects of ground bounce. See **Table 22** for the number of effective output power/ground pairs for each Virtex-E device and package combination.

Table 21: Guidelines for Max Number of Simultaneously Switching Outputs per Power/Ground Pair

Standard	Package		
	BGA, CS, FGA	HQ	PQ, TQ
LVTTL Slow Slew Rate, 2 mA drive	68	49	36
LVTTL Slow Slew Rate, 4 mA drive	41	31	20
LVTTL Slow Slew Rate, 6 mA drive	29	22	15
LVTTL Slow Slew Rate, 8 mA drive	22	17	12
LVTTL Slow Slew Rate, 12 mA drive	17	12	9
LVTTL Slow Slew Rate, 16 mA drive	14	10	7
LVTTL Slow Slew Rate, 24 mA drive	9	7	5
LVTTL Fast Slew Rate, 2 mA drive	40	29	21
LVTTL Fast Slew Rate, 4 mA drive	24	18	12
LVTTL Fast Slew Rate, 6 mA drive	17	13	9
LVTTL Fast Slew Rate, 8 mA drive	13	10	7
LVTTL Fast Slew Rate, 12 mA drive	10	7	5
LVTTL Fast Slew Rate, 16 mA drive	8	6	4
LVTTL Fast Slew Rate, 24 mA drive	5	4	3
LVCMOS	10	7	5
PCI	8	6	4
GTL	4	4	4
GTL+	4	4	4

Table 44: Bidirectional I/O Library Macros

Name	Inputs	Bidirectional	Outputs
IOBUFDS_FD_LVDS	D, T, C	IO, IOB	Q
IOBUFDS_FDE_LVDS	D, T, CE, C	IO, IOB	Q
IOBUFDS_FDC_LVDS	D, T, C, CLR	IO, IOB	Q
IOBUFDS_FDCE_LVDS	D, T, CE, C, CLR	IO, IOB	Q
IOBUFDS_FDP_LVDS	D, T, C, PRE	IO, IOB	Q
IOBUFDS_FDPE_LVDS	D, T, CE, C, PRE	IO, IOB	Q
IOBUFDS_FDR_LVDS	D, T, C, R	IO, IOB	Q
IOBUFDS_FDRE_LVDS	D, T, CE, C, R	IO, IOB	Q
IOBUFDS_FDS_LVDS	D, T, C, S	IO, IOB	Q
IOBUFDS_FDSE_LVDS	D, T, CE, C, S	IO, IOB	Q
IOBUFDS_LD_LVDS	D, T, G	IO, IOB	Q
IOBUFDS_LDE_LVDS	D, T, GE, G	IO, IOB	Q
IOBUFDS_LDC_LVDS	D, T, G, CLR	IO, IOB	Q
IOBUFDS_LDCE_LVDS	D, T, GE, G, CLR	IO, IOB	Q
IOBUFDS_LDP_LVDS	D, T, G, PRE	IO, IOB	Q
IOBUFDS_LDPE_LVDS	D, T, GE, G, PRE	IO, IOB	Q

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	- Numerous minor edits. - Data sheet upgraded to Preliminary. - Preview -8 numbers added to Virtex-E Electrical Characteristics tables.
8/1/00	1.6	- Reformatted entire document to follow new style guidelines. - Changed speed grade values in tables on pages 35-37.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply. This is the time required to reach the nominal power supply voltage of the device¹ from 0V. The fastest ramp rate is 0V to nominal voltage in 2 ms, and the slowest allowed ramp rate is 0V to nominal voltage in 50 ms. For more details on power supply requirements, see XAPP158 on www.xilinx.com.

Product (Commercial Grade)	Description ⁽²⁾	Current Requirement ⁽³⁾
XCV50E - XCV600E	Minimum required current supply	500 mA
XCV812E - XCV2000E	Minimum required current supply	1 A
XCV2600E - XCV3200E	Minimum required current supply	1.2 A
Virtex-E Family, Industrial Grade	Minimum required current supply	2 A

Notes:

1. Ramp rate used for this specification is from 0 - 1.8 V DC. Peak current occurs on or near the internal power-on reset threshold and lasts for less than 3 ms.
2. Devices are guaranteed to initialize properly with the minimum current available from the power supply as noted above.
3. Larger currents might result if ramp rates are forced to be faster.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL ⁽¹⁾	- 0.5	0.8	2.0	3.6	0.4	2.4	24	- 24
LVC MOS2	- 0.5	0.7	1.7	2.7	0.4	1.9	12	- 12
LVC MOS18	- 0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	$V_{CCO} - 0.4$	8	- 8
PCI, 3.3 V	- 0.5	30% V_{CCO}	50% V_{CCO}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
GTL	- 0.5	$V_{REF} - 0.05$	$V_{REF} + 0.05$	3.6	0.4	n/a	40	n/a
GTL+	- 0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.6	n/a	36	n/a
HSTL I ⁽³⁾	- 0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	8	- 8
HSTL III	- 0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	24	- 8
HSTL IV	- 0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCO} - 0.4$	48	- 8
SSTL3 I	- 0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.6$	$V_{REF} + 0.6$	8	- 8
SSTL3 II	- 0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.8$	$V_{REF} + 0.8$	16	- 16
SSTL2 I	- 0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.61$	$V_{REF} + 0.61$	7.6	- 7.6
SSTL2 II	- 0.5	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	$V_{REF} - 0.80$	$V_{REF} + 0.80$	15.2	- 15.2

Calculation of $T_{i\text{oop}}$ as a Function of Capacitance

$T_{i\text{oop}}$ is the propagation delay from the O Input of the IOB to the pad. The values for $T_{i\text{oop}}$ are based on the standard capacitive load (C_{sl}) for each I/O standard as listed in [Table 3](#).

Table 3: Constants for Use in Calculation of $T_{i\text{oop}}$

Standard	Csl (pF)	fl (ns/pF)
LVTTL Fast Slew Rate, 2mA drive	35	0.41
LVTTL Fast Slew Rate, 4mA drive	35	0.20
LVTTL Fast Slew Rate, 6mA drive	35	0.13
LVTTL Fast Slew Rate, 8mA drive	35	0.079
LVTTL Fast Slew Rate, 12mA drive	35	0.044
LVTTL Fast Slew Rate, 16mA drive	35	0.043
LVTTL Fast Slew Rate, 24mA drive	35	0.033
LVTTL Slow Slew Rate, 2mA drive	35	0.41
LVTTL Slow Slew Rate, 4mA drive	35	0.20
LVTTL Slow Slew Rate, 6mA drive	35	0.10
LVTTL Slow Slew Rate, 8mA drive	35	0.086
LVTTL Slow Slew Rate, 12mA drive	35	0.058
LVTTL Slow Slew Rate, 16mA drive	35	0.050
LVTTL Slow Slew Rate, 24mA drive	35	0.048
LVC MOS2	35	0.041
LVC MOS18	35	0.050
PCI 33 MHZ 3.3 V	10	0.050
PCI 66 MHZ 3.3 V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:

- I/O parameter measurements are made with the capacitance values shown above. See the application examples (in Module 2 of this data sheet) for appropriate terminations.
- I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

For other capacitive loads, use the formulas below to calculate the corresponding $T_{i\text{oop}}$:

$$T_{i\text{oop}} = T_{i\text{oop}} + T_{\text{opadjust}} + (C_{\text{load}} - C_{sl}) * fl$$

where:

T_{opadjust} is reported above in the Output Delay Adjustment section.

C_{load} is the capacitive load for the design.

Table 4: Delay Measurement Methodology

Standard	V_L^1	V_H^1	Meas. Point	V_{REF} (Typ) ²
LVTTL	0	3	1.4	-
LVC MOS2	0	2.5	1.125	-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	0.80
GTL+	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.0
HSTL Class I	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.75
HSTL Class III	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL Class IV	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
SSTL3 I & II	$V_{REF} - 1.0$	$V_{REF} + 1.0$	V_{REF}	1.5
SSTL2 I & II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.25
CTT	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.5
AGP	$V_{REF} - (0.2 \times V_{CCO})$	$V_{REF} + (0.2 \times V_{CCO})$	V_{REF}	Per AGP Spec
LVDS	1.2 - 0.125	1.2 + 0.125	1.2	
LVPECL	1.6 - 0.3	1.6 + 0.3	1.6	

Notes:

- Input waveform switches between V_L and V_H .
- Measurements are made at V_{REF} (Typ), Maximum, and Minimum. Worst-case values are reported.
I/O parameter measurements are made with the capacitance values shown in [Table 3](#). See the application examples (in Module 2 of this data sheet) for appropriate terminations.
I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Date	Version	Revision
07/23/01	2.2	- Under Absolute Maximum Ratings, changed (T_{SOL}) to 220 °C. - Changes made to SSTL symbol names in IOB Input Switching Characteristics Standard Adjustments table.
07/26/01	2.3	Removed T_{SOL} parameter and added footnote to Absolute Maximum Ratings table.
9/18/01	2.4	Reworded power supplies footnote to Absolute Maximum Ratings table.
10/25/01	2.5	- Updated the speed grade designations used in data sheets, and added Table 1, which shows the current speed grade designation for each device. - Added XCV2600E and XCV3200E values to DC Characteristics Over Recommended Operating Conditions and Power-On Power Supply Requirements tables.
11/09/01	2.6	Updated the Power-On Power Supply Requirements table.
02/01/02	2.7	Updated footnotes to the DC Input and Output Levels and DLL Clock Tolerance, Jitter, and Phase Information tables.
07/17/02	2.8	- Data sheet designation upgraded from Preliminary to Production. - Removed mention of MIL-M-38510/605 specification. - Added link to XAPP158 from the Power-On Power Supply Requirements section.
09/10/02	2.9	- Revised V_{IN} in Absolute Maximum Ratings table. - Added Clock CLK switching characteristics to Table 2, “IOB Input Switching Characteristics,” on page 6 and IOB Output Switching Characteristics, Figure 1.
12/22/02	2.9.1	- Added footnote regarding V_{IN} PCI compliance to Absolute Maximum Ratings table. - The fastest ramp rate is 0V to nominal voltage in 2 ms
03/14/03	2.9.2	Under Power-On Power Supply Requirements, the fastest ramp rate is no longer a "suggested" rate.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
[Introduction and Ordering Information \(Module 1\)](#)
- DS022-2, Virtex-E 1.8V FPGAs:
[Functional Description \(Module 2\)](#)
- DS022-3, Virtex-E 1.8V FPGAs:
DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
[Pinout Tables \(Module 4\)](#)

Table 4: CS144 — XCV50E, XCV100E, XCV200E

Bank	Pin Description	Pin #
1	VCCO	A13
1	VCCO	D7
2	VCCO	B12
3	VCCO	G11
3	VCCO	M13
4	VCCO	N13
5	VCCO	N1
5	VCCO	N7
6	VCCO	M2
7	VCCO	B2
7	VCCO	G2
NA	GND	A1
NA	GND	B9
NA	GND	B11
NA	GND	C7
NA	GND	D5
NA	GND	E4
NA	GND	E11
NA	GND	F1
NA	GND	G10
NA	GND	J1
NA	GND	J12
NA	GND	L3
NA	GND	L5
NA	GND	L7
NA	GND	L9
NA	GND	N12

Notes:

1. V_{REF} or I/O option only in the XCV200E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV100E, 200E; otherwise, I/O option only.

CS144 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A $\checkmark$ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 5: CS144 Differential Pin Pair Summary
XCV50E, XCV100E, XCV200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	K7	N8	NA	IO_DLL_L18P
1	5	M7	M6	NA	IO_DLL_L18N
2	1	A7	B7	NA	IO_DLL_L2P
3	0	A6	C6	NA	IO_DLL_L2N
IO LVDS					
Total Pairs: 30, Asynchronous Output Pairs: 18					
0	0	A4	B4	$\checkmark$	VREF
1	0	A5	B5	$\checkmark$	-
2	1	B7	C6	NA	IO_LVDS_DLL
3	1	D8	C8	$\checkmark$	-
4	1	D9	C9	$\checkmark$	VREF
5	1	D10	C10	$\checkmark$	CS, WRITE
6	2	C11	C12	$\checkmark$	DIN, D0
7	2	D13	E10	1	D1, VREF
8	2	E12	E13	$\checkmark$	D2
9	2	F10	F11	1	D3, VREF
10	3	F13	G13	NA	-
11	3	H12	H11	1	D4, VREF
12	3	H10	J13	$\checkmark$	D5
13	3	J11	J10	1	D6, VREF
14	3	K10	L13	$\checkmark$	INIT
15	4	L11	M11	$\checkmark$	-
16	4	N10	K9	$\checkmark$	VREF
17	4	N9	K8	$\checkmark$	-

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P137	VCCINT	NA
P104	VCCINT	NA
P88	VCCINT	NA
P77	VCCINT	NA
P43	VCCINT	NA
P32	VCCINT	NA
P16	VCCINT	NA
P240	VCCO	7
P232	VCCO	0
P226	VCCO	0
P212	VCCO	0
P207	VCCO	1
P197	VCCO	1
P180	VCCO	1
P176	VCCO	2
P165	VCCO	2
P150	VCCO	2
P146	VCCO	3
P136	VCCO	3
P121	VCCO	3
P116	VCCO	4
P105	VCCO	4
P90	VCCO	4
P85	VCCO	5
P76	VCCO	5
P61	VCCO	5
P55	VCCO	6
P44	VCCO	6
P30	VCCO	6
P25	VCCO	7
P15	VCCO	7
P233	GND	NA
P227	GND	NA

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P219	GND	NA
P211	GND	NA
P204	GND	NA
P196	GND	NA
P190	GND	NA
P182	GND	NA
P172	GND	NA
P166	GND	NA
P158	GND	NA
P151	GND	NA
P143	GND	NA
P135	GND	NA
P129	GND	NA
P119	GND	NA
P112	GND	NA
P106	GND	NA
P98	GND	NA
P91	GND	NA
P83	GND	NA
P75	GND	NA
P69	GND	NA
P59	GND	NA
P51	GND	NA
P45	GND	NA
P37	GND	NA
P29	GND	NA
P22	GND	NA
P14	GND	NA
P8	GND	NA
P1	GND	NA

Notes:

1. V_{REF} or I/O option only in the XCV100E, 200E, 300E, 400E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E, 400E; otherwise, I/O option only.
3. V_{REF} or I/O option only in the XCV400E; otherwise, I/O option only.

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
4	IO_L70N_Y	AK4
4	IO_L71P_YY	AJ5
4	IO_L71N_YY	AH6
4	IO_VREF_L72P_YY	AL4
4	IO_L72N_YY	AK5
4	IO_L73P_Y	AJ6
4	IO_L73N_Y	AH7
4	IO_L74P_YY	AL5
4	IO_L74N_YY	AK6
4	IO_VREF_L75P_YY	AJ7
4	IO_L75N_YY	AL6
4	IO_L76P_Y	AH9
4	IO_L76N_Y	AJ8
4	IO_VREF_L77P_Y	AK8 ¹
4	IO_L77N_Y	AJ9
4	IO_VREF_L78P_YY	AL8
4	IO_L78N_YY	AK9
4	IO_L79P_YY	AK10
4	IO_L79N_YY	AL10
4	IO_L80P_YY	AH12
4	IO_L80N_YY	AK11
4	IO_L81P_YY	AJ12
4	IO_L81N_YY	AK12
4	IO_L82P_YY	AH13
4	IO_L82N_YY	AJ13
4	IO_VREF_L83P_YY	AL13
4	IO_L83N_YY	AK14
4	IO_L84P_Y	AH14
4	IO_L84N_Y	AJ14
4	IO_VREF_L85P_Y	AK15 ²
4	IO_L85N_Y	AJ15
4	IO_LVDS_DLL_L86P	AH15
5	GCK1	AK16
5	IO	AH20
5	IO	AJ19

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
5	IO	AJ23
5	IO	AJ24
5	IO_LVDS_DLL_L86N	AL17
5	IO_L87P_Y	AK17
5	IO_VREF_L87N_Y	AJ17 ²
5	IO_L88P_Y	AH17
5	IO_L88N_Y	AK18
5	IO_L89P_YY	AL19
5	IO_VREF_L89N_YY	AJ18
5	IO_L90P_YY	AH18
5	IO_L90N_YY	AL20
5	IO_L91P_YY	AK20
5	IO_L91N_YY	AH19
5	IO_L92P_YY	AJ20
5	IO_L92N_YY	AK21
5	IO_L93P_YY	AJ21
5	IO_L93N_YY	AL22
5	IO_L94P_YY	AJ22
5	IO_VREF_L94N_YY	AK23
5	IO_L95P_Y	AH22
5	IO_VREF_L95N_Y	AL24 ¹
5	IO_L96P_Y	AK24
5	IO_L96N_Y	AH23
5	IO_L97P_YY	AK25
5	IO_VREF_L97N_YY	AJ25
5	IO_L98P_YY	AL26
5	IO_L98N_YY	AK26
5	IO_L99P_Y	AH25
5	IO_L99N_Y	AL27
5	IO_L100P_YY	AJ26
5	IO_VREF_L100N_YY	AK27
5	IO_L101P_YY	AH26
5	IO_L101N_YY	AL28
5	IO_L102P_Y	AJ27
5	IO_L102N_Y	AK28

Table 21: FG676 Differential Pin Pair Summary
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	5	AD11	Y12	√	-
121	5	AB11	AD10	NA	-
122	5	AC11	AE10	√	-
123	5	AC10	AA11	√	-
124	5	Y11	AD9	1	-
125	5	AB10	AF9	√	-
126	5	AD8	AA10	√	VREF
127	5	AE8	Y10	√	-
128	5	AC9	AF8	1	VREF
129	5	AF7	AB9	1	-
130	5	AA9	AF6	√	-
131	5	AC8	AC7	√	VREF
132	5	AD6	Y9	√	-
133	5	AE5	AA8	√	-
134	5	AC6	AB8	√	VREF
135	5	AD5	AA7	√	-
136	5	AF4	AC5	2	-
137	6	AC3	AA5	√	-
138	6	AB4	AC2	√	-
139	6	AA4	W6	2	-
140	6	Y5	AB3	1	VREF
141	6	V7	AB2	1	-
142	6	Y4	AB1	√	-
143	6	W5	V5	√	VREF
144	6	V6	AA1	√	-
145	6	Y3	W4	2	-
146	6	U7	Y1	1	VREF
147	6	V4	W1	√	-
148	6	U6	W2	√	VREF
149	6	T5	V3	√	-
150	6	U4	U5	√	-
151	6	U3	T7	2	-
152	6	T6	U2	1	-
153	6	T4	U1	1	-

Table 21: FG676 Differential Pin Pair Summary
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	6	T3	R7	1	-
155	6	R6	R4	√	VREF
156	6	R5	R3	√	-
157	6	P7	P8	2	-
158	6	P6	R1	1	VREF
159	6	P4	P5	√	-
160	7	N8	N5	√	-
161	7	N3	N6	√	-
162	7	M2	N4	1	VREF
163	7	M7	N7	2	-
164	7	M3	M6	√	-
165	7	M5	M4	√	VREF
166	7	L7	L3	1	-
167	7	K2	L6	1	-
168	7	K1	L4	1	-
169	7	L5	K3	2	-
170	7	J3	K5	√	-
171	7	J4	K4	√	-
172	7	K6	H3	√	VREF
173	7	G3	K7	√	-
174	7	H1	J5	1	VREF
175	7	J6	G2	2	-
176	7	F1	J7	√	-
177	7	G4	H4	√	VREF
178	7	H5	F3	1	-
179	7	H6	E2	2	-
180	7	F4	G5	1	VREF
181	7	G6	H7	2	-
182	7	E4	E3	√	-

Notes:

1. AO in the XCV600E.
2. AO in the XCV400E.

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	6	AP39	AP38	4	-
189	6	AN38	AN36	6	VREF
190	6	AN39	AN37	√	-
191	6	AM38	AM36	4	-
192	6	AL36	AM37	6	-
193	6	AL37	AM39	√	VREF
194	6	AK36	AL38	√	-
195	6	AK37	AL39	7	VREF
196	6	AJ36	AK38	4	-
197	6	AJ37	AK39	√	VREF
198	6	AH37	AJ38	√	-
199	6	AH38	AJ39	4	-
200	6	AG38	AH39	√	VREF
201	6	AG39	AG36	√	-
202	6	AF39	AG37	6	-
203	6	AE38	AF36	4	-
204	6	AF38	AF37	4	-
205	6	AE36	AE39	6	VREF
206	6	AE37	AD38	√	-
207	6	AD36	AD39	4	-
208	6	AC39	AC38	6	-
209	6	AB38	AD37	√	VREF
210	6	AB39	AC35	√	-
211	6	AA38	AC36	7	-
212	6	AA39	AC37	4	-
213	6	Y38	AB35	√	VREF
214	6	Y39	AB36	√	-
215	6	AA36	AB37	4	VREF
216	7	W38	AA37	√	-
217	7	V39	W37	4	VREF
218	7	U39	W36	√	-
219	7	U38	V38	√	VREF
220	7	T39	V37	4	-
221	7	T38	V36	7	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
222	7	R39	V35	√	-
223	7	U36	U37	√	VREF
224	7	U35	R38	6	-
225	7	T37	P39	4	-
226	7	T36	P38	√	-
227	7	N38	N39	6	VREF
228	7	M39	R37	4	-
229	7	M38	R36	4	-
230	7	L39	P37	6	-
231	7	N37	P36	√	-
232	7	N36	L38	√	VREF
233	7	M37	K39	4	-
234	7	L37	K38	√	-
235	7	L36	J39	√	VREF
236	7	K37	J38	4	-
237	7	K36	H39	√	VREF
238	7	J37	H38	√	-
239	7	G38	G39	√	VREF
240	7	F39	J36	6	-
241	7	F38	H37	4	-
242	7	E39	H36	√	-
243	7	E38	G37	6	VREF
244	7	D39	G36	4	-
245	7	F36	D38	4	VREF
246	7	E37	D37	6	-

Notes:

1. AO in the XCV1000E, 1600E, 2000E.
2. AO in the XCV600E, 1000E, 1600E.
3. AO in the XCV600E, 1000E.
4. AO in the XCV1000E, 1600E.
5. AO in the XCV1000E, 2000E.
6. AO in the XCV600E, 1000E, 2000E.
7. AO in the XCV1000E.
8. AO in the XCV2000E.

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
2	IO_D1_L87N_YY	P2
2	IO_D2_L88P_YY	P3
2	IO_L88N_YY	L4
2	IO_L89P_Y	P1
2	IO_L89N_Y	R2
2	IO_L90P_Y	M5
2	IO_L90N_Y	R3
2	IO_L91P_Y	M4
2	IO_L91N_Y	R1
2	IO_L92P	N4
2	IO_L92N	T2
2	IO_L93P_Y	P5
2	IO_L93N_Y	T3
2	IO_VREF_L94P_Y	P4
2	IO_L94N_Y	T1
2	IO_L95P_YY	U2
2	IO_L95N_YY	R4
2	IO_L96P_Y	U3
2	IO_L96N_Y	T5
2	IO_L97P_Y	T4
2	IO_L97N_Y	V2
2	IO_VREF_L98P_YY	U5
2	IO_D3_L98N_YY	V3
2	IO_L99P_YY	V1
2	IO_L99N_YY	V5
2	IO_L100P_Y	W2
2	IO_L100N_Y	V4
2	IO_L101P_Y	W5
2	IO_L101N_Y	W1
2	IO_VREF_L102P_YY	Y2
2	IO_L102N_YY	W4
2	IO_L103P_YY	Y1
2	IO_L103N_YY	Y5
2	IO_VREF_L104P_Y	AA1 ¹
2	IO_L104N_Y	Y4
2	IO_L105P_YY	AA4
2	IO_L105N_YY	AA2

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
3	IO	AB4
3	IO	AC2
3	IO	AD1
3	IO	AE3
3	IO	AF4
3	IO	AH5
3	IO	AJ2
3	IO	AL1
3	IO	AM3
3	IO	AP3
3	IO	AR5
3	IO	AU4
3	IO	AB2
3	IO_L106P_Y	AB3
3	IO_VREF_L106N_Y	AC4 ¹
3	IO_L107P_YY	AB1
3	IO_L107N_YY	AC5
3	IO_L108P_YY	AD4
3	IO_VREF_L108N_YY	AC3
3	IO_L109P_Y	AC1
3	IO_L109N_Y	AD5
3	IO_L110P_Y	AE4
3	IO_L110N_Y	AD3
3	IO_L111P_YY	AE5
3	IO_L111N_YY	AD2
3	IO_D4_L112P_YY	AE1
3	IO_VREF_L112N_YY	AF5
3	IO_L113P_Y	AE2
3	IO_L113N_Y	AG4
3	IO_L114P_Y	AG5
3	IO_L114N_Y	AF1
3	IO_L115P_YY	AH4
3	IO_L115N_YY	AF2
3	IO_L116P_Y	AF3
3	IO_VREF_L116N_Y	AJ4
3	IO_L117P_Y	AG1

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO	AJ40
6	IO	AL41
6	IO	AN38
6	IO	AN42
6	IO	AP41
6	IO	AR39
6	IO_L211N_YY	AV41
6	IO_L211P_YY	AV42
6	IO_L212N_Y	AW40
6	IO_L212P_Y	AU41
6	IO_L213N_Y	AV39
6	IO_L213P_Y	AU42
6	IO_VREF_L214N_Y	AT41
6	IO_L214P_Y	AU38
6	IO_L215N	AT42
6	IO_L215P	AV40
6	IO_L216N_Y	AR41
6	IO_L216P_Y	AU39
6	IO_VREF_L217N_Y	AR42
6	IO_L217P_Y	AU40
6	IO_L218N_YY	AT38
6	IO_L218P_YY	AP42
6	IO_L219N_Y	AN41
6	IO_L219P_Y	AT39
6	IO_L220N_Y	AT40
6	IO_L220P_Y	AM40
6	IO_VREF_L221N_YY	AR38
6	IO_L221P_YY	AM41
6	IO_L222N_YY	AM42
6	IO_L222P_YY	AR40
6	IO_VREF_L223N_Y	AL40 ²
6	IO_L223P_Y	AP38
6	IO_L224N_Y	AP39
6	IO_L224P_Y	AL42
6	IO_VREF_L225N_YY	AP40
6	IO_L225P_YY	AK40
6	IO_L226N_YY	AK41

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO_L226P_YY	AN39
6	IO_L227N_Y	AK42
6	IO_L227P_Y	AN40
6	IO_VREF_L228N_YY	AM38
6	IO_L228P_YY	AJ41
6	IO_L229N_YY	AJ42
6	IO_L229P_YY	AM39
6	IO_L230N_Y	AH40
6	IO_L230P_Y	AH41
6	IO_L231N_Y	AL38
6	IO_L231P_Y	AH42
6	IO_L232N_Y	AL39
6	IO_L232P_Y	AG41
6	IO_L233N	AK39
6	IO_L233P	AG40
6	IO_L234N_Y	AJ38
6	IO_L234P_Y	AG42
6	IO_VREF_L235N_Y	AF42
6	IO_L235P_Y	AJ39
6	IO_L236N_YY	AF41
6	IO_L236P_YY	AH38
6	IO_L237N_Y	AE42
6	IO_L237P_Y	AH39
6	IO_L238N_Y	AG38
6	IO_L238P_Y	AE41
6	IO_VREF_L239N_YY	AG39
6	IO_L239P_YY	AD42
6	IO_L240N_YY	AD40
6	IO_L240P_YY	AF39
6	IO_L241N_Y	AD41
6	IO_L241P_Y	AE38
6	IO_L242N_Y	AE39
6	IO_L242P_Y	AC40
6	IO_VREF_L243N_YY	AD38
6	IO_L243P_YY	AC41
6	IO_L244N_YY	AB42
6	IO_L244P_YY	AC38

FG860 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A $\checkmark$ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	C22	A22	NA	IO_DLL_L34N
2	1	B22	D22	NA	IO_DLL_L34P
1	5	AY22	AW21	NA	IO_DLL_L176N
0	4	BA22	AW20	NA	IO_DLL_L176P
IO LVDS					
Total Pairs: 281, Asynchronous Output Pairs: 111					
0	0	D38	A38	2	-
1	0	E37	B37	1	-
2	0	C39	A37	1	VREF
3	0	C38	B36	1	-
4	0	B35	A36	$\checkmark$	-
5	0	D37	A35	$\checkmark$	VREF
6	0	A34	C37	5	-
7	0	B33	E36	5	-
8	0	C32	A33	$\checkmark$	-
9	0	B32	C36	$\checkmark$	VREF
10	0	D35	A32	1	-
11	0	C35	C31	1	VREF
12	0	A31	E34	$\checkmark$	-
13	0	C30	D34	$\checkmark$	VREF
14	0	E33	B30	2	-
15	0	D33	A30	2	-
16	0	B29	C33	$\checkmark$	VREF
17	0	A29	E32	$\checkmark$	-

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	0	C28	D32	2	-
19	0	B28	E31	1	-
20	0	A28	D31	1	-
21	0	C27	D30	5	-
22	0	B27	E29	$\checkmark$	-
23	0	A27	D29	$\checkmark$	VREF
24	0	D28	C26	5	-
25	0	F27	B26	5	-
26	0	C25	E27	$\checkmark$	-
27	0	B25	D27	$\checkmark$	VREF
28	0	D26	A25	1	-
29	0	E25	A24	1	-
30	0	B24	D25	$\checkmark$	-
31	0	A23	E24	$\checkmark$	VREF
32	0	E23	C23	2	-
33	0	D23	B23	2	VREF
34	1	D22	A22	NA	IO_LVDS_DLL
35	1	B21	D21	2	VREF
36	1	A21	D20	2	-
37	1	D19	C20	$\checkmark$	VREF
38	1	E19	B20	$\checkmark$	-
39	1	A19	D18	1	-
40	1	C19	E18	1	-
41	1	E17	B19	$\checkmark$	VREF
42	1	D16	A18	$\checkmark$	-
43	1	B18	E16	5	-
44	1	A17	F16	5	-
45	1	E15	C17	$\checkmark$	VREF
46	1	D14	B17	$\checkmark$	-
47	1	E14	A16	5	-
48	1	D13	C16	1	-
49	1	D12	B16	1	-
50	1	E12	A15	2	-
51	1	C11	C15	$\checkmark$	-

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	5	AY27	AV28	√	-
189	5	BA27	AW29	5	-
190	5	BB28	AV29	1	-
191	5	AY28	AW30	1	-
192	5	BA28	AW31	2	-
193	5	BB29	AV31	√	-
194	5	AY29	AY32	√	VREF
195	5	AW32	BB30	2	-
196	5	AV32	AY30	2	-
197	5	BA30	AW33	√	VREF
198	5	BB31	AV33	√	-
199	5	AY34	BA31	1	VREF
200	5	AW34	BB32	1	-
201	5	BA32	AY35	√	VREF
202	5	BB33	AW35	√	-
203	5	AV35	BB34	5	-
204	5	AY36	BA34	5	-
205	5	BB35	AV36	√	VREF
206	5	BA35	AY37	√	-
207	5	BB36	BA36	5	-
208	5	AW37	BB37	1	VREF
209	5	BA37	AY38	1	-
210	5	BB38	AY39	2	-
211	6	AV42	AV41	√	-
212	6	AU41	AW40	3	-
213	6	AU42	AV39	1	-
214	6	AU38	AT41	2	VREF
215	6	AV40	AT42	4	-
216	6	AU39	AR41	2	-
217	6	AU40	AR42	1	VREF
218	6	AP42	AT38	√	-
219	6	AT39	AN41	2	-
220	6	AM40	AT40	1	-
221	6	AM41	AR38	√	VREF

Table 25: FG860 Differential Pin Pair Summary
XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
222	6	AR40	AM42	√	-
223	6	AP38	AL40	5	VREF
224	6	AL42	AP39	2	-
225	6	AK40	AP40	√	VREF
226	6	AN39	AK41	√	-
227	6	AN40	AK42	2	-
228	6	AJ41	AM38	√	VREF
229	6	AM39	AJ42	√	-
230	6	AH41	AH40	3	-
231	6	AH42	AL38	1	-
232	6	AG41	AL39	2	-
233	6	AG40	AK39	4	-
234	6	AG42	AJ38	2	-
235	6	AJ39	AF42	1	VREF
236	6	AH38	AF41	√	-
237	6	AH39	AE42	2	-
238	6	AE41	AG38	1	-
239	6	AD42	AG39	√	VREF
240	6	AF39	AD40	√	-
241	6	AE38	AD41	5	-
242	6	AC40	AE39	2	-
243	6	AC41	AD38	√	VREF
244	6	AC38	AB42	√	-
245	6	AC39	AB40	2	VREF
246	7	AB39	AA41	√	-
247	7	AA39	Y41	2	VREF
248	7	Y39	Y40	√	-
249	7	W41	Y38	√	VREF
250	7	W39	W40	2	-
251	7	V41	W38	5	-
252	7	V40	V39	√	-
253	7	U39	V42	√	VREF
254	7	U38	U41	1	-
255	7	T39	U42	2	-

Table 27: FG900 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	3	AA30	W24	4	-
121	3	AA29	V20	1	-
122	3	Y27	W23	NA	-
123	3	Y26	AB30	√	D5
124	3	V21	AA28	√	VREF
125	3	Y25	AA27	4	-
126	3	W22	Y23	4	-
127	3	Y24	AB28	4	VREF
128	3	AC30	AA25	√	-
129	3	W21	AA24	2	-
130	3	AB26	AD30	√	-
131	3	Y22	AC27	√	VREF
132	3	AD28	AB25	2	-
133	3	AC26	AE30	4	-
134	3	AD27	AF30	√	-
135	3	AF29	AB24	1	VREF
136	3	AB23	AE28	4	-
137	3	AG30	AC25	3	-
138	3	AE26	AG29	4	VREF
139	3	AH30	AC24	1	-
140	3	AF28	AD25	NA	-
141	3	AH29	AA22	√	INIT
142	4	AF27	AK28	√	-
143	4	AG26	AH27	4	-
144	4	AD23	AJ27	2	-
145	4	AB21	AF25	2	VREF
146	4	AC22	AH26	2	-
147	4	AA21	AG25	√	-
148	4	AJ26	AD22	√	VREF
149	4	AA20	AH25	1	-
150	4	AC21	AF24	1	-
151	4	AG24	AK26	√	-
152	4	AJ24	AF23	√	VREF
153	4	AE23	AB20	2	-

Table 27: FG900 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	4	AC20	AG23	2	-
155	4	AF22	AE22	√	-
156	4	AJ22	AG22	√	VREF
157	4	AK24	AD20	NA	-
158	4	AA19	AF21	4	-
159	4	AH22	AA18	NA	VREF
160	4	AG21	AK23	NA	-
161	4	AH21	AD19	4	-
162	4	AE20	AJ21	2	-
163	4	AG20	AF20	2	-
164	4	AC18	AF19	2	-
165	4	AJ20	AE19	√	-
166	4	AK22	AH20	√	VREF
167	4	AG19	AB17	1	-
168	4	AJ19	AD17	1	-
169	4	AA16	AA17	√	-
170	4	AK21	AB16	√	VREF
171	4	AG18	AK20	2	-
172	4	AK19	AD16	2	-
173	4	AE16	AE17	√	-
174	4	AG17	AJ17	√	VREF
175	4	AD15	AH17	NA	-
176	4	AG16	AK17	4	VREF
177	5	AF16	AH16	NA	IO_LVDS_DLL
178	5	AC15	AG15	4	VREF
179	5	AB15	AF15	√	-
180	5	AA15	AF14	√	VREF
181	5	AH15	AK15	√	-
182	5	AB14	AF13	2	-
183	5	AH14	AJ14	2	-
184	5	AE14	AG13	√	VREF
185	5	AK13	AD13	√	-
186	5	AE13	AF12	1	-
187	5	AC13	AA13	1	-

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
6	IO_VREF_L265N_Y	AJ3
6	IO_L265P_Y	AG5
6	IO_L266N_YY	AD9 ⁴
6	IO_L266P_YY	AJ2 ⁵
6	IO_L267N_YY	AC10
6	IO_L267P_YY	AH2
6	IO_L268N_Y	AH3
6	IO_L268P_Y	AF5
6	IO_L269N_Y	AE8 ⁴
6	IO_L269P_Y	AG3 ⁵
6	IO_L270N_Y	AE7
6	IO_L270P_Y	AG2
6	IO_VREF_L271N_YY	AF6
6	IO_L271P_YY	AG1
6	IO_L272N_YY	AC9 ⁴
6	IO_L272P_YY	AG4 ⁵
6	IO_L273N_YY	AE6
6	IO_L273P_YY	AF3
6	IO_VREF_L274N_Y	AF1 ²
6	IO_L274P_Y	AF4
6	IO_L275N	AB10 ⁴
6	IO_L275P	AF2 ⁵
6	IO_L276N_Y	AC8
6	IO_L276P_Y	AE1
6	IO_VREF_L277N_YY	AD5
6	IO_L277P_YY	AE3
6	IO_L278N_YY	AC7
6	IO_L278P_YY	AD1
6	IO_L279N_Y	AD6
6	IO_L279P_Y	AD2
6	IO_VREF_L280N_YY	AB8
6	IO_L280P_YY	AC1
6	IO_L281N_YY	AC5
6	IO_L281P_YY	AC2

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
6	IO_L282N_Y	AA9
6	IO_L282P_Y	AC3
6	IO_L283N_Y	AC4
6	IO_L283P_Y	AD4
6	IO_L284N_Y	AA8
6	IO_L284P_Y	AB6
6	IO_L285N	AB1
6	IO_L285P	Y10
6	IO_L286N_Y	AB2
6	IO_L286P_Y	AA7
6	IO_VREF_L287N_Y	AA4
6	IO_L287P_Y	AA1
6	IO_L288N_YY	Y9 ⁴
6	IO_L288P_YY	AB4 ⁵
6	IO_L289N_YY	AA2
6	IO_L289P_YY	Y8
6	IO_L290N_Y	AA6
6	IO_L290P_Y	AA5
6	IO_L291N_Y	AB3 ⁴
6	IO_L291P_Y	Y7 ⁵
6	IO_L292N_Y	Y1
6	IO_L292P_Y	W10
6	IO_VREF_L293N_YY	Y5
6	IO_L293P_YY	Y2
6	IO_L294N_YY	W9 ⁴
6	IO_L294P_YY	W2 ⁵
6	IO_L295N_YY	W7
6	IO_L295P_YY	Y4
6	IO_L296N_Y	W1
6	IO_L296P_Y	Y6
6	IO_L297N_Y	W6 ⁴
6	IO_L297P_Y	W3 ⁵
6	IO_L298N_Y	V9
6	IO_L298P_Y	W4